12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification# 20250106002.0
Datasheet for LMP7704-SP

Information Only

Date: January 22, 2025
To: MOUSER PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the Change Management team.

Sincerely,

Change Management Team
SC Business Services

20250106002.0
Information Only Datasheet
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records**,** you have recently purchased these devices**.** The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LMP7704HBH/EM	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20250106002.0	PCN Date:	January 22, 2025
Title:	Datasheet for LMP7704-SP		
Customer Contact:	Change Management team	Dept:	Quality Services
Change Type:	Electrical Specification		

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification.
The product datasheet(s) is being updated as summarized below.
The following change history provides further details.

TEXAS INSTRUMENTS — LMP7704-SP
SNOSDB6D – DECEMBER 2020 – REVISED OCTOBER 2024

Changes from Revision C (March 2022) to Revision D (October 2024) — **Page**

- Changed description of SEL characteristics from "SEL immune" to "SEL resilient" in *Features*; see also *Radiation Hardened Performance* 1
- Updated *Device Information* table notes for clarity 1
- Changed LID pin description to clarify connections between thermal pad, metal lid, and device substrate in *Pin Functions* table 3
- Updated table note 1 in *Absolute Maximum Ratings* 4
- Changed differential voltage parameter to input differential voltage, per channel, added clarifying table note, changed maximum value from (V+) – (V–) + 0.3 to 0.3 V, and added minimum value of –0.3 V, in *Absolute Maximum Ratings* 4
- Added "flight model post-HDR exposure" condition, with minimum value of 82dB, to "power-supply rejection ratio" 5
- Added "flight model post-TID exposure" condition, with maximum value of ±400 pA, to "input bias current" 5
- Added table note to "common-mode voltage", clarifying input differential voltage limitations 5
- Added "flight model post-HDR exposure" condition, with minimum value of 82 dB, to "power-supply rejection ratio" 6
- Added "flight model post-TID exposure" condition, with maximum value of ±400 pA, to "input bias current" 6
- Added table note to "common-mode voltage", clarifying input differential voltage limitations, and added "T_A = –55°C to +125°C" condition 6
- Changed description of TID RLAT levels from 30-krad, 50-krad, and 100-krad, to 100-krad(Si) in *Radiation Hardened Performance* 15
- Changed description of NDD test levels from 15 units irradiated up to 1 × 10^{12} n/cm^2, to 12 units irradiated up to 1 × 10^{13} n/cm^2, and summarized test results in *Radiation Hardened Performance* 15
- Added discussion of application-specific SEE concerns in *Radiation Hardened Performance* 15
- Changed decoupling capacitor guidance from "10-nF to 1-µF" to "1nF to 100nF" in *Power Supply Recommendations* 22
- Added text discussing bulk decoupling capacitance isolation for SEE-mitigation in *Power Supply Recommendations* 22
- Added guidance regarding power pad and lid metalization to *Layout Guidelines* 23
- Deleted "LMP7704-SP Example Layout for a Single Channel" figure, and replaced with "LMP7704-SP Example Layout" figure, in *Layout Example* 23
- Added "LMP7704-SP Supply Decoupling Capacitance Example Layout" figure in *Layout Example* 23
- Added *Related Documentation* section 24
- Deleted outdated and incorrect HBH0014A package outline drawing from *Mechanical, Packaging, and Orderable Information* 25

The datasheet number will be changing.

Device Family	Change From:	Change To:
LMP7704-SP	SNOSDB6C	**SNOSDB6D**

These changes may be reviewed at the datasheet links provided. http://www.ti.com/product/LMP7704-SP
Reason for Change:
To accurately reflect device characteristics.
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):
No anticipated impact.
Changes to product identification resulting from this PCN:
None.
Product Affected:

5962R1920601VXC	LMP7704HBH/EM		

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.